

MODIFIED CHIP ATTACH PROCESS AND APPARATUS

Abstract of the Disclosure

5 A method of packaging a die includes reflowing the solder to electrically
connect the die to a substrate at a first temperature, cooling the die and substrate to a
second temperature, and placing a heated epoxy in contact with the die and the
substrate. The method also includes holding the die and substrate at the second
temperature for a time sufficient to allow the epoxy to cure, and cooling the die,
10 substrate and epoxy. The second temperature is less than the first temperature. In
addition, the die and substrate are not cooled to a temperature significantly below
the second temperature until after the heated epoxy is placed in contact with the die
and substrate.

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